

Title (en)
METHOD FOR JOINING RESIN AND METAL

Title (de)
VERFAHREN ZUM FÜGEN VON KUNSTSTOFF UND METALL

Title (fr)
PROCÉDÉ POUR CONNECTER DU PLASTIQUE ET DU METAL

Publication
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Application
EP 09786104 A 20090804

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Abstract (en)
[origin: WO2010020850A1] A method and an apparatus for joining a resin member (4) and a metal member (3) by heating, wherein the joining of the resin member and metal member is performed by heating a joining interface of the resin member and metal member to a temperature in a range of equal to or higher than a decomposition temperature of the resin member and lower than a temperature at which gas bubbles are generated in the resin member and by cooling a surface of the resin member on the opposite side from a joining surface thereof with the metal member to a temperature that is lower than the melting point of the resin member.

IPC 8 full level
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CPC (source: EP KR US)
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